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(54) Title: POWER CABLE COMPOSITIONS FOR STRIPPABLE ADHESION

(57) Abstract: The present invention is a semiconductive power cable composition made from or containing (a) a mixture of a hightemperature polymer and a soft polymer, and (b) a conductive filler, wherein a semiconductive cable layer prepared from the composition strippably adheres to a second cable layer. The invention also includes a semiconductive cable layer prepared from the semiconductive power cable composition as well as a power cable construction prepared by applying the semiconductive cable layer over a wire or cable.

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